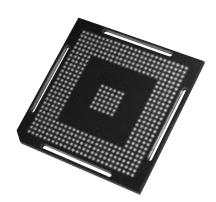
# **Ball Grid Array** (BGA) Adapters



5 Energy Way, West Warwick, RI 02893 USA Tel: 800-424-9850 / 401-823-5200 Fax: 401-823-8723 E-mail: info@advintcorp.com Internet: www.advintcorp.com



### Adapter Features

- Soldering BGA to Adapter subjects BGA to less thermal stress than soldering BGA directly to a PCB due to Adapter's lower mass.
- Uses same footprint as BGA device.
- · Custom Adapters available for heat sink attachments.

# **Specifications**

#### Terminals:

Brass; Copper Alloy (C36000), ASTM-B-16

#### Plating:

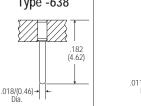
G - Gold over Nickel

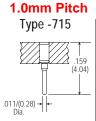
### **Body Material:**

F - FR-4 Glass Epoxy, U.L. Rated 94V-0

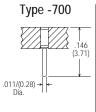
### **Terminals**

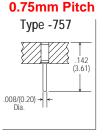
# 1.27mm and 1.5mm Pitch Type -638





### 0.80mm Pitch



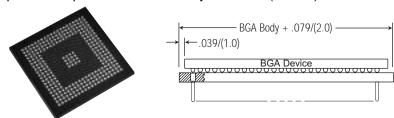


## Standard Adapter (A)

Mates with Standard Socket (S)

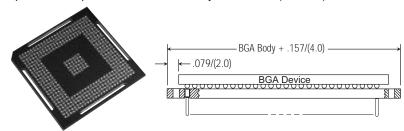
Now Available In 0.75mm Pitch

Adapter size equals BGA device body + .079 in. (2.0mm)



## **Extraction Slot Adapter (AX)**

- Slots allow easy device/Adapter assembly removal from socket with Advanced® Extraction Tool without damaging valuable PCB
- Mates with Extraction Socket (SB) or Guide Post Socket (SG)
- Adapter size equals BGA device body + .157 in. (4.0mm)



## **Advanced® BGA Adapter Extraction Tools**



# **How To Order – BGA Adapters**

